

Datasheet revision 1.0

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ROL0 No-Clean Tack Flux in a 30cc/30g syringe w/plunger & tips

Product Highlights

More Robust, Higher Activity, Better Wetting, No-Clean

Ideal for all rework, solder, de-solder and reflow applications Non-corrosive, non-conductive Tack flux will not run all over PCB when applied Has a pleasant odor Excellent wetting Easily cleaned with isopropyl alcohol (IPA) Attachment of BGA spheres Soldering flip chip components Long stencil life Wide process window Clear residue Can be used with Leaded and Lead-Free applications **RoHS 3 and REACH compliant**



Specifications

Flux Type:Synthetic No-Clean (for Leaded and Lead-Free applications)Flux Classification:ROL0Flux Activation Temperature:140°C (284°F)Packaging:30cc/30g Luer Lock Syringe w/plunger & tipsShelf Life:Refrigerated >24 months, Unrefrigerated >24 months

Stencil Life >8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following Industry Standards: J-STD-004B, Amendment 1 (Solder Fluxes): RoHS 3 Directive (EU) 2015/863:

Yes Yes